

PRODUCT SPECIFICATION For CF20 Series Connector System

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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and inserted on the specified size FPC and FFC

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part
	design standards

- 3. APPLICABLE SERIES NO.: CF20 Series
- 4. SHAPE, CONSTRUCTION AND DIMENSIONS See attached drawings
- 5. MATERIALS See attached drawings
- 6. ACCOMMODATED P.C.BOARD6.1 Thickness: 0.5 mm (.020") ~ 2.0 mm (.079")6.2 P.C. Board Layout: See attached drawings
- 7. ACCOMMODATED FPC/FFC THICKNESS 0.3 +0.04/-0.01 mm (.012+.002/-0")



REVIEWED : <u>Eisley</u> APPROVED : <u>Eisley</u> VERIFIED : <u>Hank</u>.



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8. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Rated current and voltage		For 0.5mm Pitch: 0.4A max. 50V AC/DC max. For 1.0mm Pitch: 0.4A max. 100V AC/DC max.
8.2	Contact resistance	Dry circuit of DC 20 mV max., 100 mA max.	Less than 30 m Ω
8.3	Dielectric strength	For 0.5mm Pitch: When applied AC 250 V 1 minute between adjacent terminal For 1.0mm Pitch: When applied AC 500 V 1 minute between adjacent terminal	No change
8.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 100 M Ω

9. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Contact retaining force in insulator	Retention speed 25± 3 mm per minute from housing	More than 0.2 Kgf(1.96N)
9.2	FFC / FPC withdrawal force (Reference data)	Measure force to withdrawal using 0.30 mm thickness FPC / FFC at speed 25± 3 mm per minute	Standard: (0.02× no. of Contacts) Kgf min. (0.196× no. of Contacts) N min.
9.3	Separation force of slider and base	Pull out the slider from the base at speed 25± 3 mm per minute	More than 2.0 Kgf(19.6N)
9.4	Durability	Connector shall be subjected to 20 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial



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10. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
10.1	Temperature rise	Then carried the rated current	30°C max.
10.2	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
10.3	Solder ability	Tin-Lead Process:	Minimum:
		Soldering time: 5 ± 0.5 second	90% of immersed area
		Soldering pot: 230 ± 5°C	
		Lead-Free Process	
		Soldering time: 3 ± 0.5 second	
		Soldering pot: 245 ± 5°C	
10.4	Resistance to soldering heat	Tin-Lead Process	No damage
		Refer Reflow temperature profile(12.1)	
		Soldering time: 10 second Max.	
		Soldering pot: 230 ± 5 °C	
		Lead-Free Process	
		Refer Reflow temperature profile(12.2)	
		Soldering time: 20 second Max.	
		Soldering pot: 250~260°C	
10.5	Heat aging	85 ± 2°C , 96 hours	No damage
10.6	Humidity	40 ± 2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 8-3
10.7	Temperature cycling	One cycle consists of : (1) -55^{+0}_{-3} °C , 30 min. (2)Room temp. 10-15 min. (3) 85^{+3}_{-0} °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial



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	ITEM	TEST CONDITION	REQUIREMENT
10.8	Salt spray	Temperature: 35 ± 3 °C	Appearance: No damage
		Solution: $5 \pm 1\%$	Contact resistance:
		Spray time: 48 ± 4 hours	Less than twice of initial
		Measurement must be taken after water rinse	

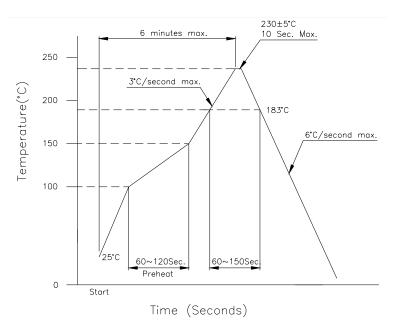
11. AMBIENT TEMPERATURE RANGE: -25 to + 85°C



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12. Recommended IR Reflow Temperature Profile:

12.1 Using Typical Solder Paste



12.2 Using Lead-Free Solder Paste

